

REGULATORY COMPLIANCE

 <p>Lead Free COMPLIANT</p>	 <p>EU RoHS 2011/65 + 2015/863 COMPLIANT</p>	 <p>China RoHS COMPLIANT</p>	 <p>REACH SVHC COMPLIANT</p>	 <p>DRC CONFLICT FREE</p>
--	--	--	--	---

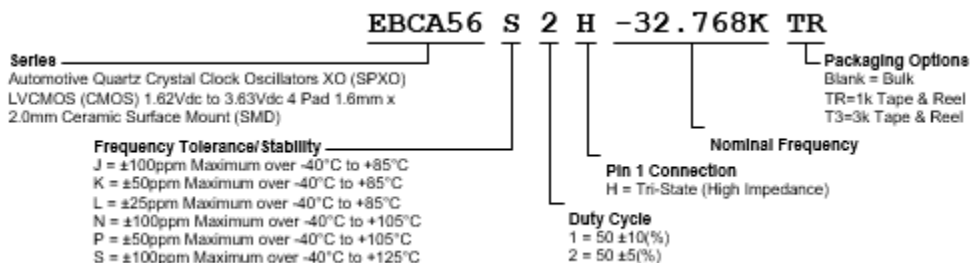
ITEM DESCRIPTION

Automotive Grade Quartz Crystal Clock Oscillators XO (SPXO) LVCMOS (CMOS) 1.62Vdc to 3.63Vdc 4 Pad 1.6mm x 2.0mm Ceramic Surface Mount (SMD)

ELECTRICAL SPECIFICATIONS

Nominal Frequency	32.768kHz
Frequency Tolerance/Stability	Inclusive of all conditions: Calibration Tolerance (at 25°C), Frequency Stability over the Operating Temperature Range, Supply Voltage Change ($\pm 5\%$), Output Load Change ($\pm 5\%$), and First Year Aging at 25°C $\pm 100\text{ppm}$ Maximum over -40°C to $+85^\circ\text{C}$ $\pm 50\text{ppm}$ Maximum over -40°C to $+85^\circ\text{C}$ $\pm 25\text{ppm}$ Maximum over -40°C to $+85^\circ\text{C}$ $\pm 100\text{ppm}$ Maximum over -40°C to $+105^\circ\text{C}$ $\pm 50\text{ppm}$ Maximum over -40°C to $+105^\circ\text{C}$ $\pm 100\text{ppm}$ Maximum over -40°C to $+125^\circ\text{C}$
Aging at 25°C	$\pm 3\text{ppm/year}$ Maximum
Supply Voltage	1.62Vdc to 3.63Vdc
Input Current	Unloaded, Vdd = 3.3Vdc 50 μA Typical, 100 μA Maximum
Output Voltage Logic High (Voh)	IOH = -1mA 90% of Vdd Minimum
Output Voltage Logic Low (Vol)	IOL = +1mA 10% of Vdd Maximum
Rise/Fall Time	Measured at 10% to 90% of Waveform 15nSec Maximum
Duty Cycle	Measured at 50% of Waveform 50 $\pm 10\%$ 50 $\pm 5\%$
Load Drive Capability	15pF Maximum
Output Logic Type	CMOS
Pin 1 Connection	Tri-State (High Impedance)
Output Control Input Voltage Logic High (Vih)	70% of Vdd Minimum or No Connect to Enable Output
Output Control Input Voltage Logic Low (Vil)	30% of Vdd Maximum to Disable Output (High Impedance)
Standby Current	Disable Output: High Impedance 1 μA Typical, 3 μA Maximum
Start Up Time	2mSec Maximum
Storage Temperature Range	-55°C to $+125^\circ\text{C}$

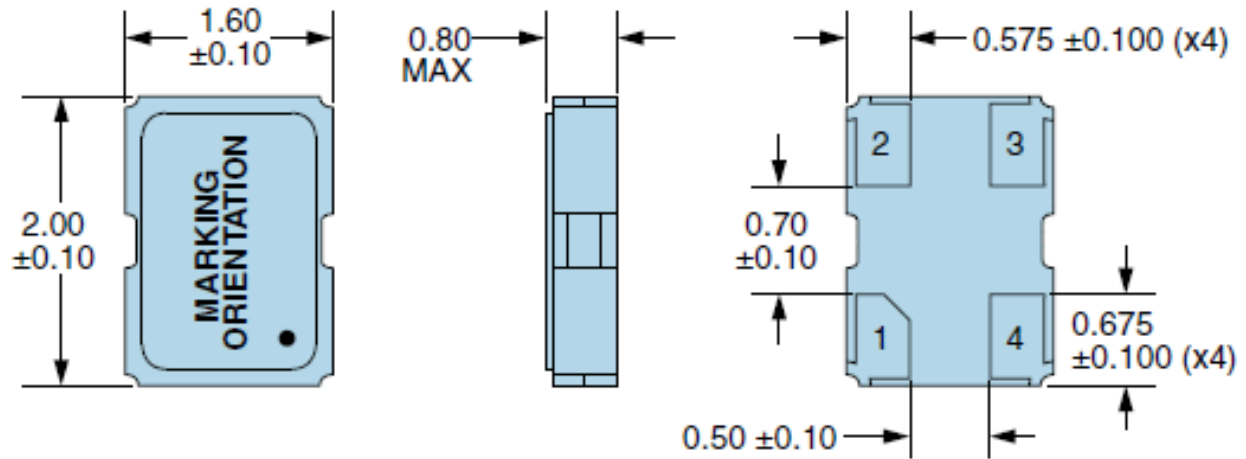
PART NUMBERING GUIDE



ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

ESD Susceptibility	MIL-STD-883, Method 3015, Class 1, HBM: 1500V
Fine Leak Test	MIL-STD-883, Method 1014, Condition A
Flammability	UL94-V0
Gross Leak Test	MIL-STD-883, Method 1014, Condition C
Mechanical Shock	MIL-STD-883, Method 2002, Condition B
Moisture Resistance	MIL-STD-883, Method 1004
Moisture Sensitivity	J-STD-020, MSL 1
Resistance to Soldering Heat	MIL-STD-202, Method 210, Condition K
Resistance to Solvents	MIL-STD-202, Method 215
Solderability	MIL-STD-883, Method 2003
Temperature Cycling	MIL-STD-883, Method 1010, Condition B
Vibration	MIL-STD-883, Method 2007, Condition A

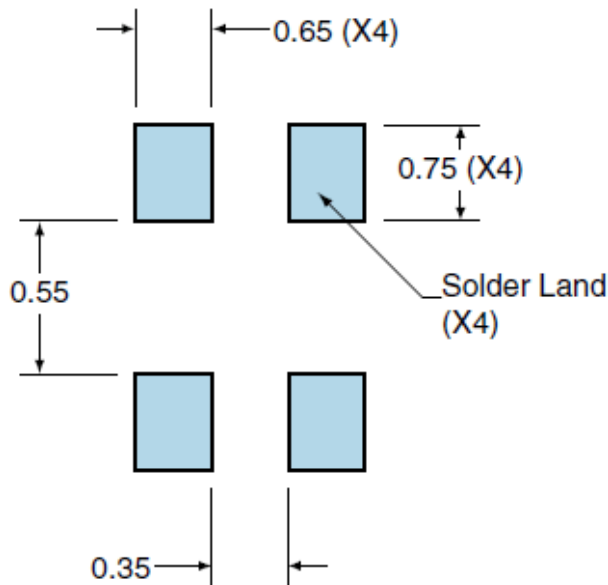
MECHANICAL DIMENSIONS



Seam Sealed

Terminal Plating Thickness: Gold (0.3 to 1.0µm) over Nickel (1.27 to 8.89µm).

SUGGESTED SOLDER PAD LAYOUT

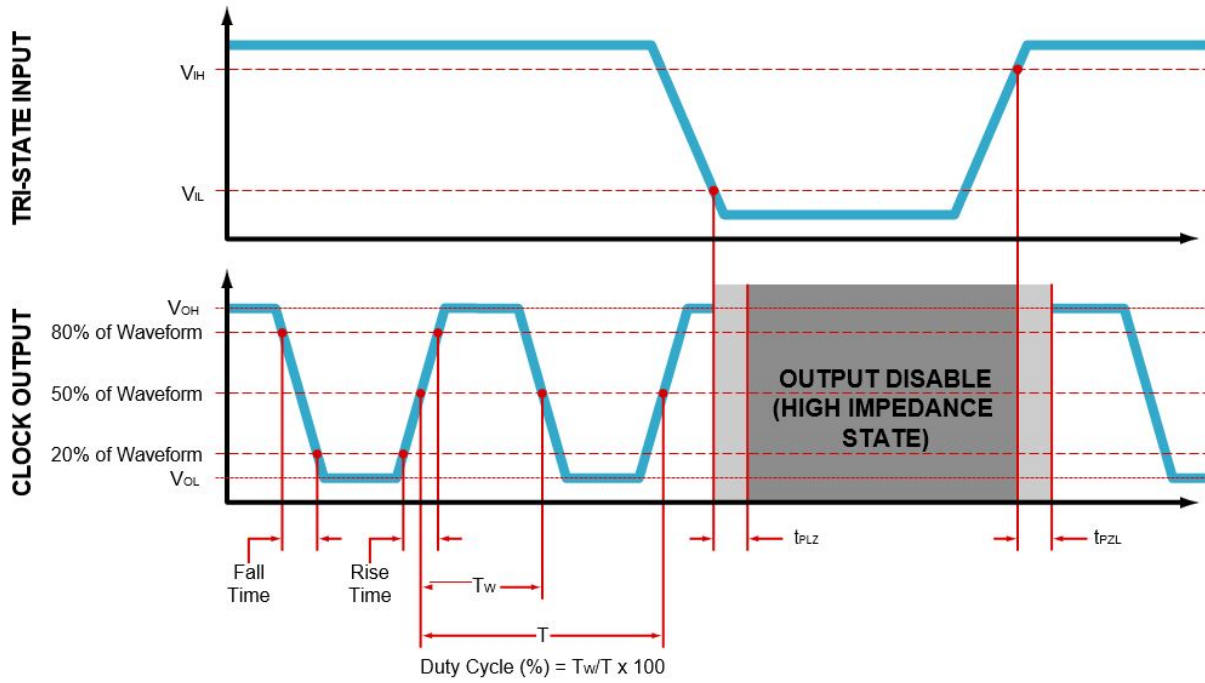


PIN	CONNECTION
1	Tri-State
2	Case/Ground
3	Output
4	Supply Voltage

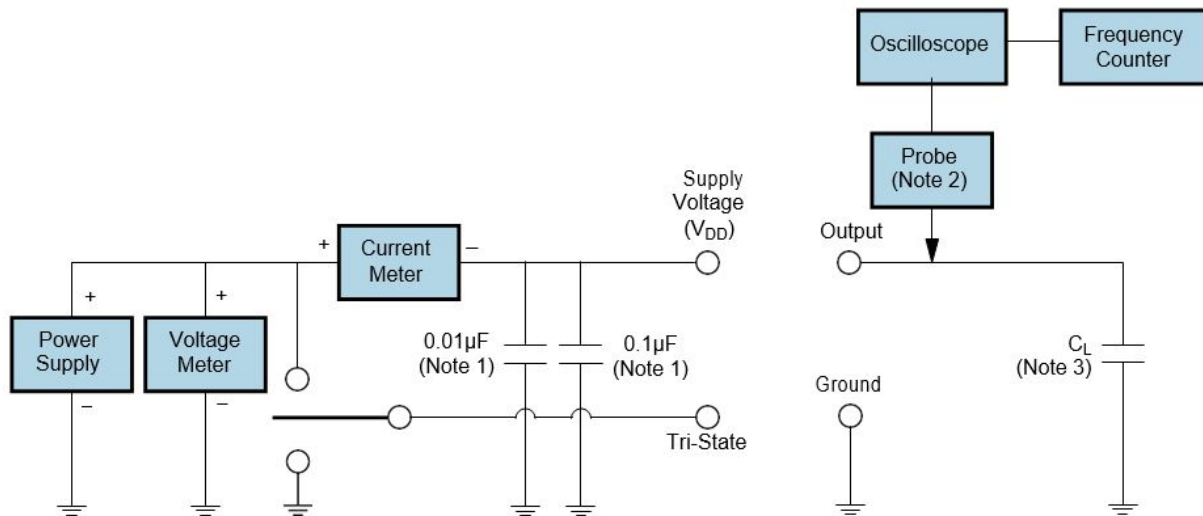
All Tolerances are ±0.1

All Dimensions in Millimeters

OUTPUT WAVEFORM & TIMING DIAGRAM



TEST CIRCUIT FOR CMOS OUTPUT



Note 1: An external 0.01µF ceramic bypass capacitor in parallel with a 0.1µF high frequency ceramic bypass capacitor close (less than 2mm) to the package ground and supply voltage pin is required.

Note 2: A low capacitance (<12pF), 10X Attenuation Factor, High Impedance (>10Mohms), and High bandwidth (>300MHz) Passive probe is recommended.

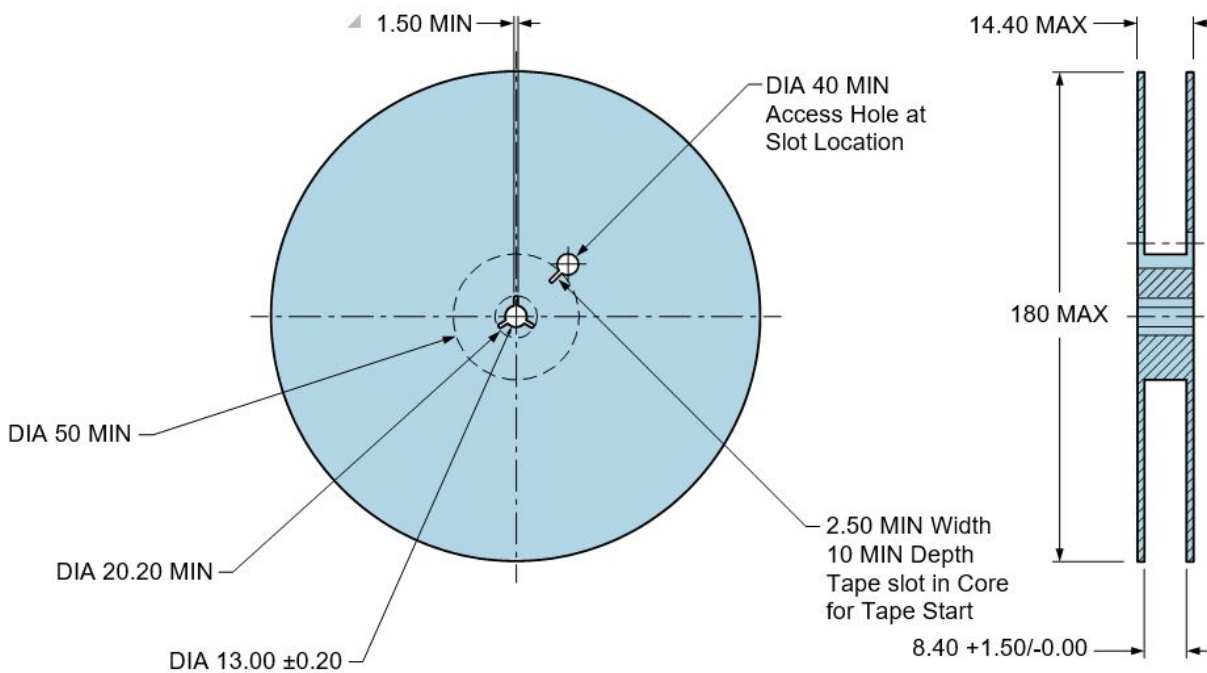
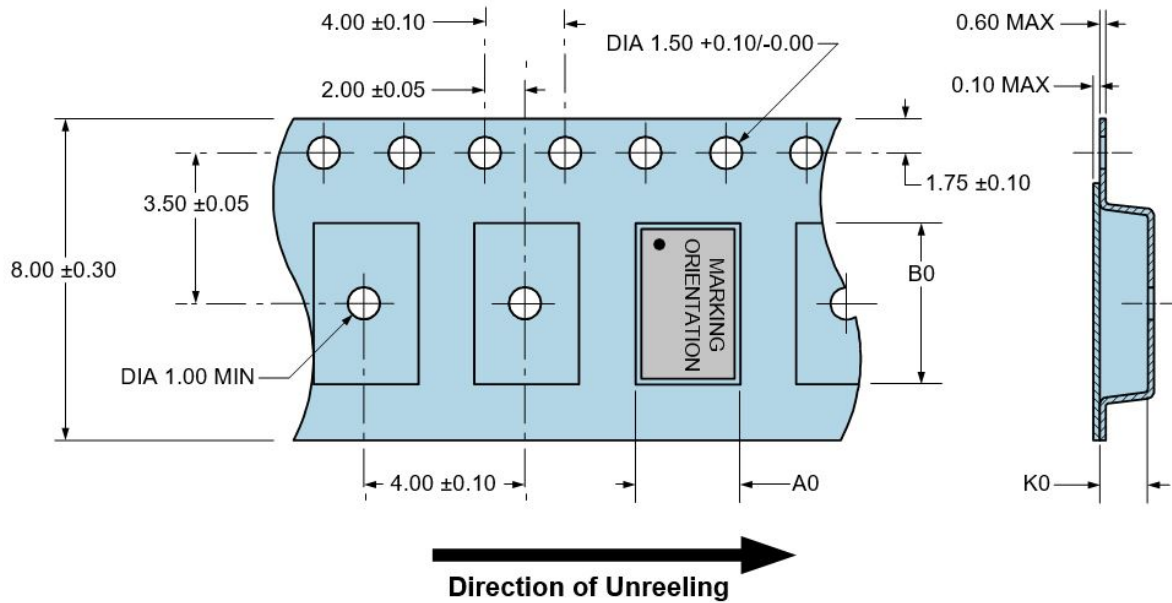
Note 3: Capacitance value C_L includes sum of all probe and fixture capacitance.

TAPE & REEL DIMENSIONS

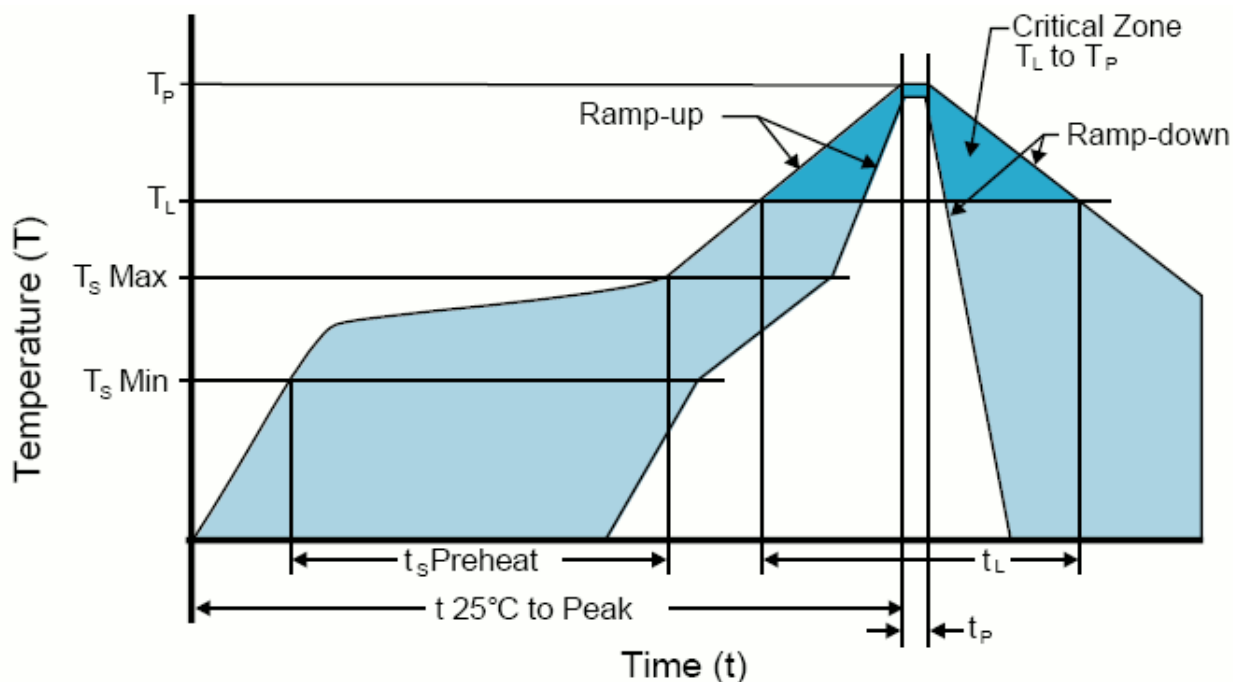
Quantity per Reel: TR= 1000 or T3=3000 Units

All Dimensions in Millimeters

Compliant to EIA-481



RECOMMENDED SOLDER REFLOW METHOD



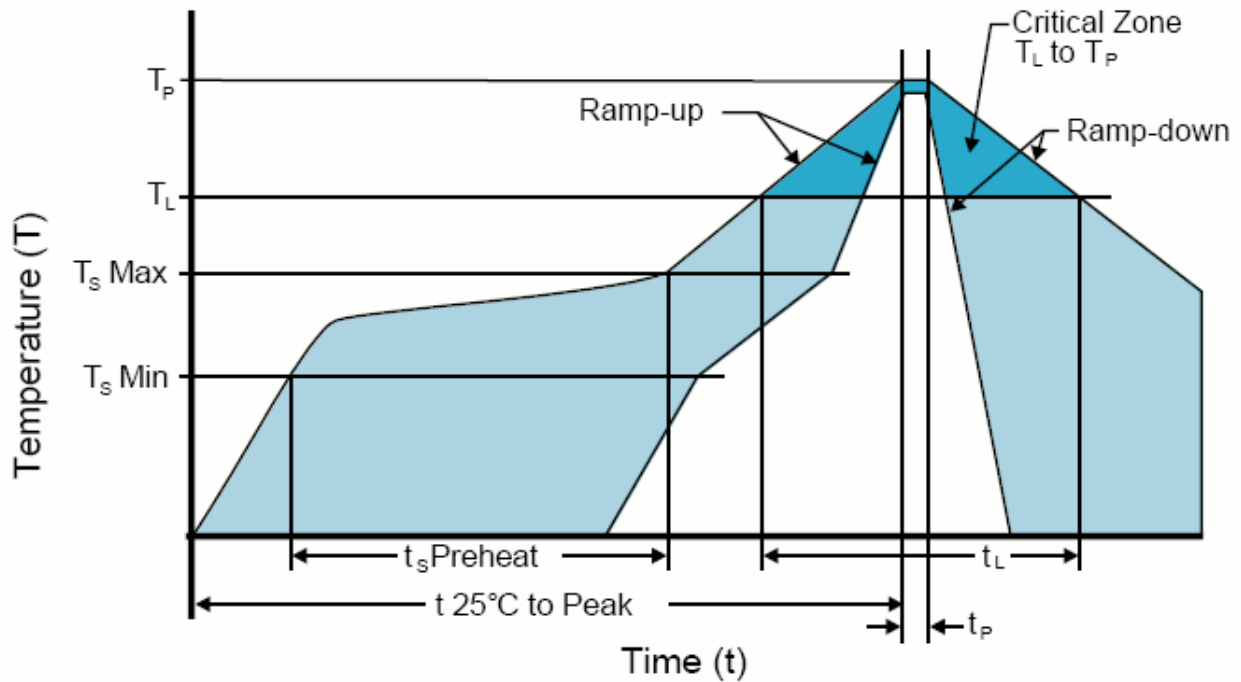
HIGH TEMPERATURE INFRARED/CONVECTION

T _S MAX to T _L (Ramp-up Rate)	3°C/Second Maximum
Preheat	
- Temperature Minimum (T _S MIN)	150°C
- Temperature Typical (T _S TYP)	175°C
- Temperature Maximum(T _S MAX)	200°C
- Time (t _s MIN)	60 - 180 Seconds
Ramp-up Rate (T _L to T _P)	3°C/Second Maximum
Time Maintained Above:	
- Temperature (T _L)	217°C
- Time (t _L)	60 - 150 Seconds
Peak Temperature (T _P)	260°C Maximum for 10 Seconds Maximum
Target Peak Temperature(T _P Target)	250°C +0/-5°C
Time within 5°C of actual peak (t _p)	20 - 40 Seconds
Ramp-down Rate	6°C/Second Maximum
Time 25°C to Peak Temperature (t)	8 Minutes Maximum
Moisture Sensitivity Level	Level 1
Additional Notes	Temperatures shown are applied to body of device.

High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)

RECOMMENDED SOLDER REFLOW METHOD



LOW TEMPERATURE INFRARED/CONVECTION

T _S MAX to T _L (Ramp-up Rate)	5°C/Second Maximum
Preheat	
- Temperature Minimum (T _S MIN)	N/A
- Temperature Typical (T _S TYP)	150°C
- Temperature Maximum(T _S MAX)	N/A
- Time (t _s MIN)	60 - 120 Seconds
Ramp-up Rate (T _L to T _P)	5°C/Second Maximum
Time Maintained Above:	
- Temperature (T _L)	150°C
- Time (t _L)	200 Seconds Maximum
Peak Temperature (T _P)	240°C Maximum
Target Peak Temperature(T _P Target)	240°C Maximum 2 Times/230°C Maximum 1Time
Time within 5°C of actual peak (t _P)	10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time
Ramp-down Rate	5°C/Second Maximum
Time 25°C to Peak Temperature (t)	N/A
Moisture Sensitivity Level	Level 1
Additional Notes	Temperatures shown are applied to body of device.

Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

[ABRACON:](#)

[EBCA56K2H-32.768k TR](#)